

Title of the Invention:

METHOD OF BENDING OUTSIDE LEADS OF SEMICONDUCTOR PACKAGE
AND AN APPARATUS THEREFOR

Abstract

A roll bending method wherein a plurality of parallel leads of a semiconductor package is formed into a predetermined shape by rotating a die about a rotational axis, such that an end portion of each of the leads is pressed inward and bent into a shape conforming to the shape of the die. The roll bending is performed using a roll bending device including a die having an operating surface, a holding member for securing the package in a fixed position so that a portion of each of the leads is brought into engagement with the operating surface of the die, and means for rotating the die about such a rotational axis as to simultaneously bend the leads.

FIG. 2